

EVVOSEMI[®]

THINK CHANGE DO



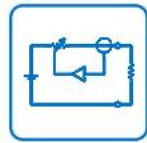
ESD



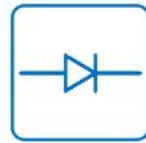
TVS



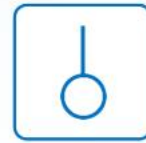
MOS



LDO



Diode



Sensor



DC-DC

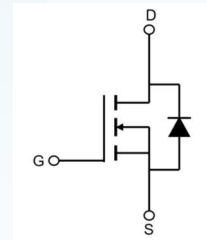
Product Specification

▶ Domestic	Part Number	IRF1010ES
▶ Overseas	Part Number	IRF1010ES
▶ Equivalent	Part Number	IRF1010ES

EV is the abbreviation of name EVVO

Feature

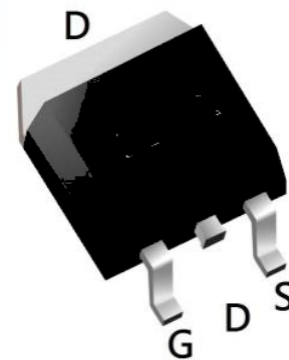
- 60V,80A
 $R_{DS(on)} < 10m\Omega @ V_{GS}=10V$
 $R_{DS(on)} < 14m\Omega @ V_{GS}=4.5V$
- Advanced Trench Technology
- Lead free product is acquired
- Excellent $R_{DS(on)}$ and Low Gate Charge



Schematic Diagram

Application

- PWM applications
- Load Switch
- Power management



ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_a = 25^\circ\text{C}$)	I_D	80	A
Continuous Drain Current ($T_a = 100^\circ\text{C}$)	I_D	56	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	232	A
Singel Pulsed Avalanche Energy ⁽²⁾	E_{AS}	110	mJ
Power Dissipation	P_D	70	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.14	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS (T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	60	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 60V, V _{GS} = 0V	-	-	1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±100	nA
Gate threshold voltage ⁽³⁾	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1	1.7	2.5	V
Drain-source on-resistance ⁽³⁾	R _{DS(on)}	V _{GS} = 10V, I _D = 30A	-	7.5	10	mΩ
		V _{GS} = 4.5V, I _D = 20A	-	10	14	
Forward transconductance ⁽³⁾	g _{FS}	V _{DS} = 10V, I _D = 30A	20	-	-	S
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz	-	4400	-	pF
Output Capacitance	C _{oss}		-	210	-	
Reverse Transfer Capacitance	C _{rss}		-	190	-	
Switching characteristics						
Turn-on delay time	t _{d(on)}	V _{DD} = 30V, I _D = 30A, R _L = 1Ω V _{GS} = 10V, R _G = 3Ω	-	7.1	-	ns
Turn-on rise time	t _r		-	5.3	-	
Turn-off delay time	t _{d(off)}		-	27.2	-	
Turn-off fall time	t _f		-	6.2	-	
Total Gate Charge	Q _g	V _{DS} = 30V, I _D = 30A, V _{GS} = 10V	-	77	-	nC
Gate-Source Charge	Q _{gs}		-	9	-	
Gate-Drain Charge	Q _{gd}		-	23	-	
Source-Drain Diode characteristics						
Diode Forward voltage ⁽³⁾	V _{DS}	V _{GS} = 0V, I _S = 30A	-	-	1.2	V
Diode Forward current ⁽⁴⁾	I _S		-	-	80	A
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25° , I _F = 30A, di/dt = 100A/us		29		ns
Body Diode Reverse Recovery Charge	Q _{rr}	T _J = 25° , I _F = 30A, di/dt = 100A/us		45		nc

Notes:

1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: T_J = 25°C, V_{DD} = 20V, R_G = 25 Ω, L = 0.5mH, I_{AS} = 21A
3. Pulse Test: pulse width ≤ 300μs, duty cycle ≤ 2%
4. Surface Mounted on FR4 Board, t ≤ 10 sec

Test Circuit

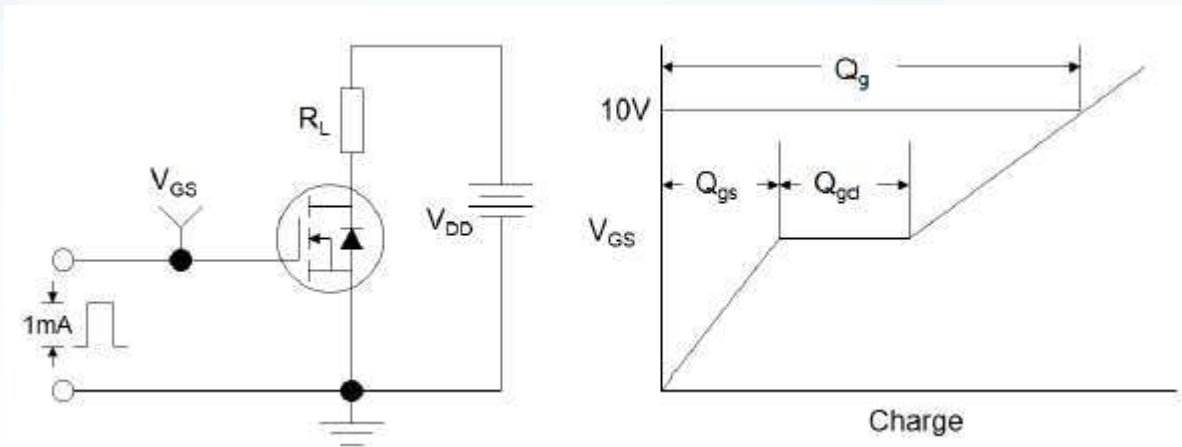


Figure 1: Gate Charge Test Circuit & Waveform

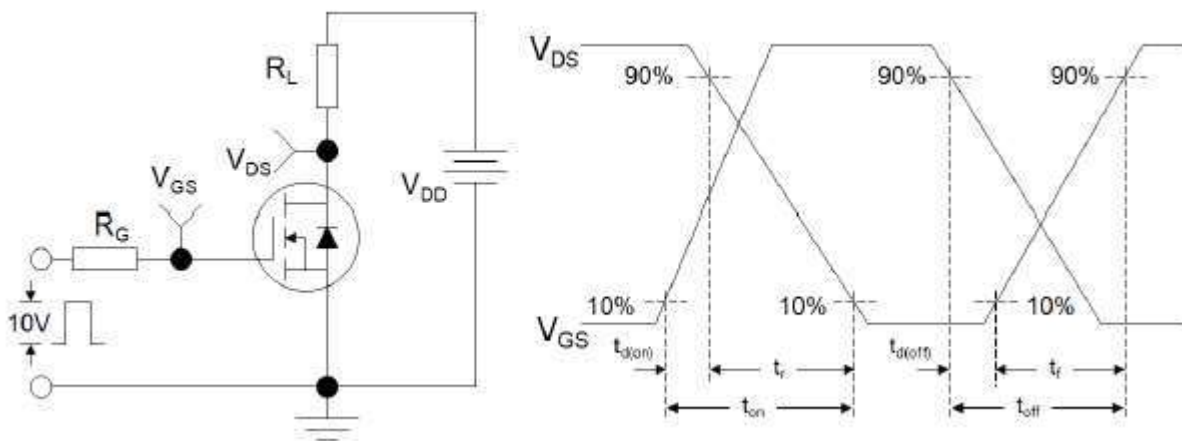


Figure 2: Resistive Switching Test Circuit & Waveforms

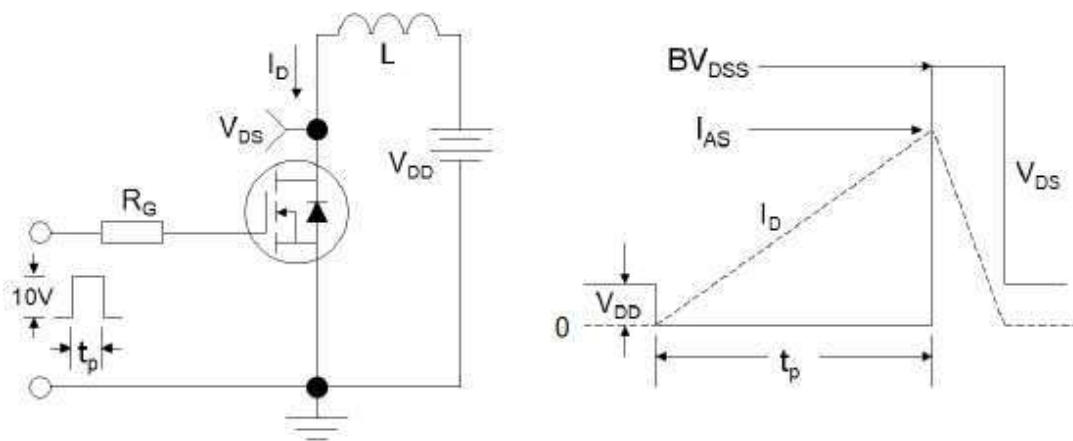


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

Figure 1: Output Characteristics

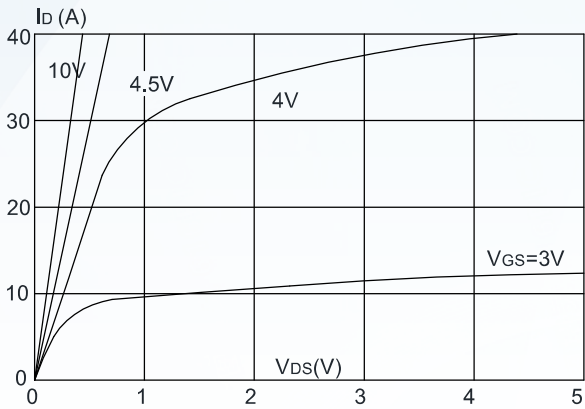


Figure 2: Typical Transfer Characteristics

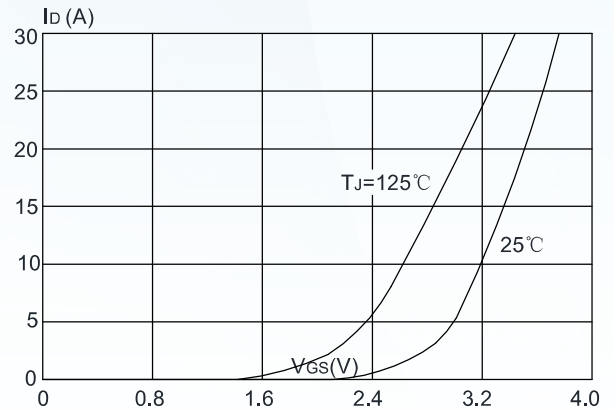


Figure 3: On-resistance vs. Drain Current

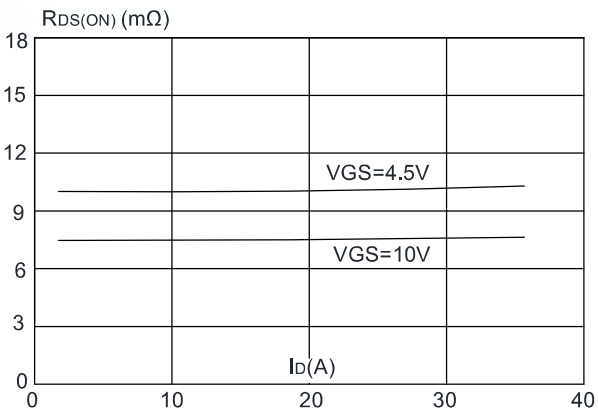


Figure 4: Body Diode Characteristics

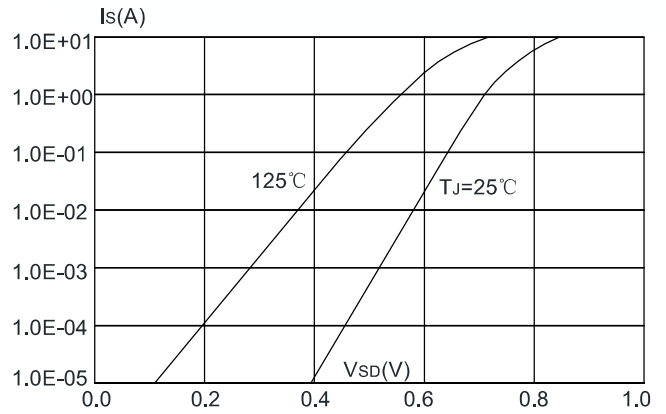


Figure 5: Gate Charge Characteristics

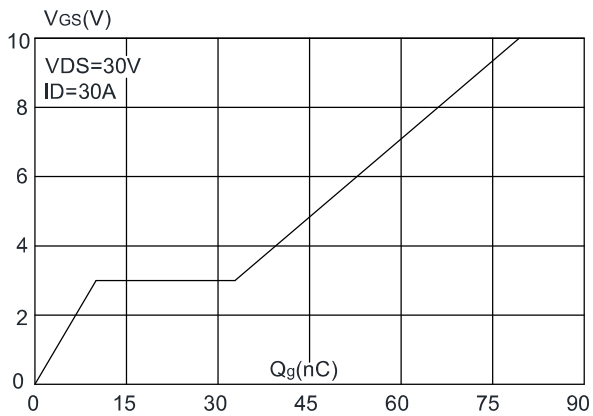


Figure 6: Capacitance Characteristics

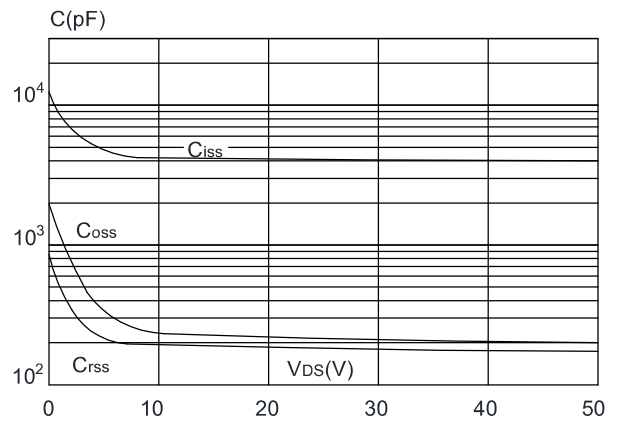


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

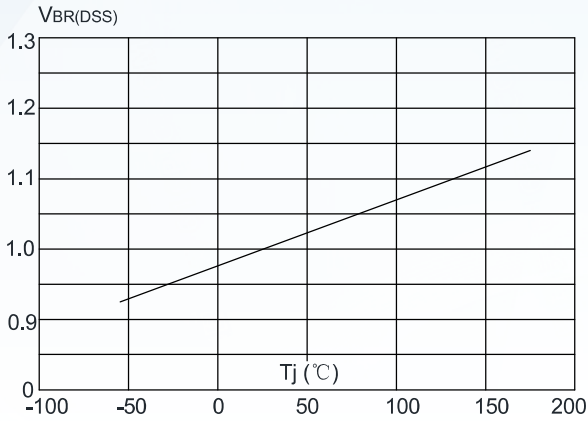


Figure 8: Normalized on Resistance vs. Junction Temperature

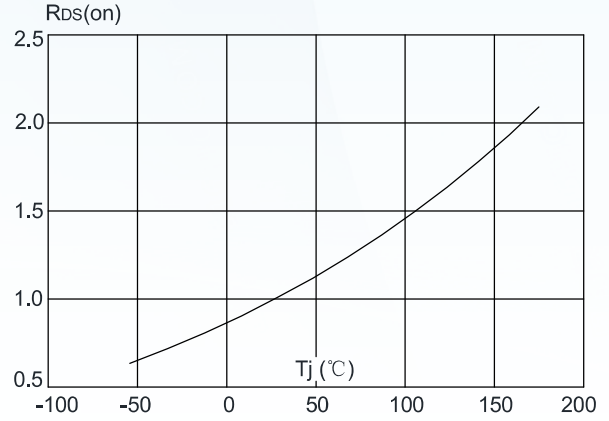


Figure 9: Maximum Safe Operating Area

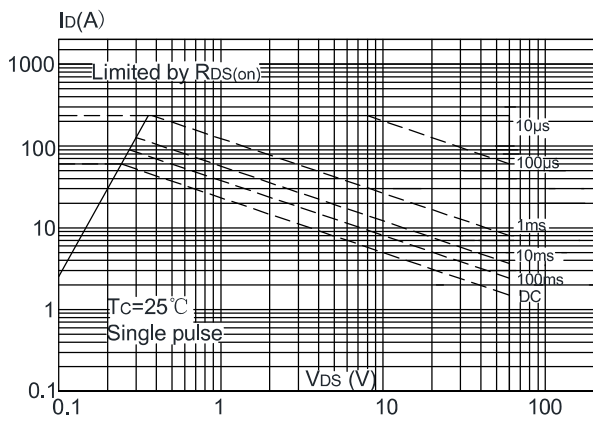


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

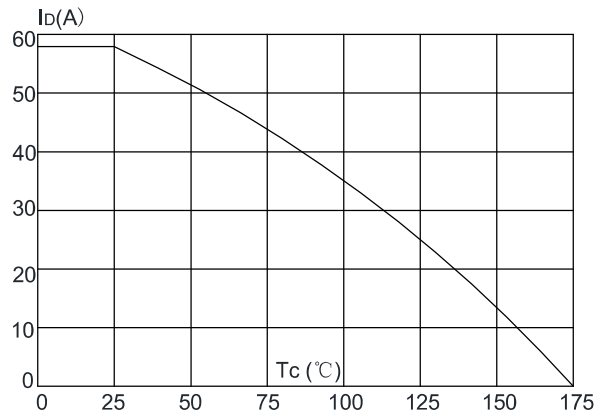
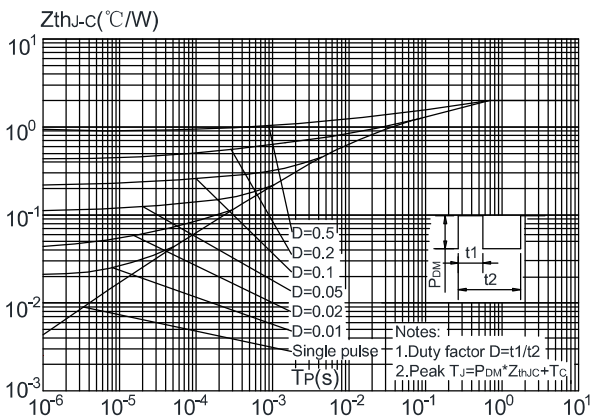


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



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